

Layer Name	Order	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	1.4mil	12.6mil	FR-4	4.80	Core
MidLayer1	(.G1)	1.4mil	30mil	FR-4	4.80	PrePreg
MidLayer2	(.G2)	1.4mil	12.6mil	FR-4	4.80	Core
Bottom Layer	(.GBL)	1.4mil	12.6mil	FR-4	4.80	Core
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
1500mil X 3000mil

Number of Layers : 4
 MIN. TRACK WIDTH: 7 MIL
 MIN. CLEARANCE: 7 MIL
 MIN. VIA PAD SIZE: 22 MIL

MINIMUM ANNULAR RING 0.15mm (6MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG)
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

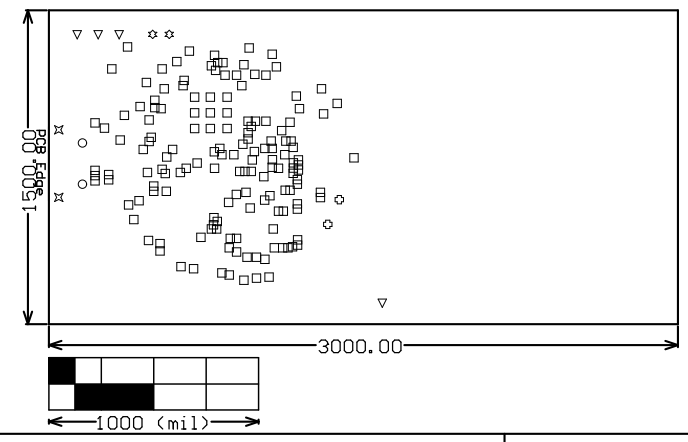
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S ID/LOGO: RAIL METAL SILK

Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
□	151	10mil (0.254mm)			PTH	Round
☆	2	31.5mil (0.8mm)			PTH	Round
▽	4	40mil (1.016mm)			PTH	Round
⊗	2	63mil (1.6mm)			PTH	Round
○	2	31.496mil (0.8mm)	39.37mil (1mm)	7.874mil (0.2mm)	PTH	Slot
⊗	2	31.496mil (0.8mm)	51.181mil (1.3mm)	19.685mil (0.5mm)	PTH	Slot
	163 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
 Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table



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